Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-17. (Canceled)

18. (Currently Amended) A method for fabricating a membrane of a structural material for a micro-device, comprising:

forming a first layer of a first material;

forming a first layer of structural material over the first layer of the first material;

forming at least one cut in the first layer of structural material;

forming a first layer of a sacrificial material, less resistant to removal than the first material, over the first layer of structural material such that an interface is created between the first material and the sacrificial material at the at least one cut in the first layer of structural material;

forming a second layer of structural material over the first layer of sacrificial material; and

subjecting the first layer of sacrificial material to a release etch to remove the first layer of the sacrificial material such that the second layer of structural material forms the membrane for the micro-device.

19. (Original) The method of claim 18, wherein forming the first layer of structural material comprises forming a layer of polysilicon.

20. (Original) The method of claim 18, wherein forming the first layer of structural material comprises forming a layer of single crystal silicon.

21. (Original) The method of claim 18, wherein forming the at least one cut in the first layer of structural material comprises forming at least one channel.

22. (Original) The method of claim 18, wherein:

forming the first layer of the first material comprises forming a first layer of nitride; and

forming the first layer of the sacrificial material comprises forming a first layer of oxide.

23. (Canceled).

24. (Previously Presented) The method of claim 18, further comprising:

forming a second layer of a sacrificial material over the second layer of structural material;

forming a protective layer over the second layer of the sacrificial material;

forming at least one cut in the protective layer;

forming a second layer of a second material over the protective layer such that an interface is created between the second layer of the second material and the second layer of the sacrificial material at the at least one cut in the protective layer; and

subjecting the second layer of the sacrificial material to the release etch to remove the second layer of the sacrificial material.

25. (Currently Amended) A method for fabricating a membrane of a structural material for a micro-device, comprising:

forming a first layer of a first material;

forming a first layer of structural material over the first layer of the first material;

forming at least one cut in the first layer of structural material;

forming a first layer of a sacrificial material, less resistant to removal than the first material, over the first layer of structural material such that an interface is created between the first material and the sacrificial material at the at least one cut in the first layer of structural material;

forming a second layer of structural material over the first layer of sacrificial material;

subjecting the first layer of sacrificial material to a release etch to remove the first layer of the sacrificial material forming a second layer of a sacrificial material over the second layer of structural material;

forming a protective layer over the second layer of the sacrificial material;

forming at least one cut in the protective layer;

forming a second layer of a second material over the protective layer such that an interface is created between the second layer of the second material and the second layer of the sacrificial material at the at least one cut in the protective layer;

subjecting the second layer of the sacrificial material to the release etch to remove the second layer of the sacrificial material; and

~~The method of claim 23, further comprising~~ removing the protective layer after subjecting the first and second layers of sacrificial materials to the release etch.

26. (Original) The method of claim 25, wherein removing the protective layer is accomplished mechanically.

27. (Original) The method of claim 25, wherein removing the protective layer is accomplished chemically.

28. (Original) The method of claim 24, wherein forming the first layer of structural material comprises forming a layer of polysilicon.

29. (Original) The method of claim 24, wherein forming the protective layer comprises forming a protective layer of polysilicon.

30. (Original) The method of claim 24, wherein forming the first layer of structural material comprises forming a layer of single crystal silicon.

31. (Original) The method of claim 24, wherein forming the protective layer comprises forming a protective layer of single crystal silicon.

32. (Currently Amended) A method for fabricating a membrane of a structural material for a micro-device, comprising:

forming a first layer of a first material;

forming a first layer of structural material over the first layer of the first material;

forming at least one cut in the first layer of structural material;

forming a first layer of a sacrificial material, less resistant to removal than the first material, over the first layer of structural material such that an interface is created between the first material and the sacrificial material at the at least one cut in the first layer of structural material;

forming a second layer of structural material over the first layer of sacrificial material;

subjecting the first layer of sacrificial material to a release etch to remove the first layer of the sacrificial material forming a second layer of a sacrificial material over the second layer of structural material;

forming a protective layer over the second layer of the sacrificial material;

forming at least one cut in the protective layer;

forming a second layer of a second material over the protective layer such that an interface is created between the second layer of the second material and the second layer of the sacrificial material at the at least one cut in the protective layer;

subjecting the second layer of the sacrificial material to the release etch to remove the second layer of the sacrificial material; and

~~The method of claim 24,~~ wherein:

forming the first layer of the first material comprises forming a first layer of nitride;

forming the first layer of the sacrificial material comprises forming a first layer of oxide;

forming the second layer of the second material comprises forming a second layer of nitride; and

forming the second layer of the sacrificial material comprises forming a second layer of oxide.

33-36. (Canceled)